



DFX

Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 61212  
Application ID: 10774893  
Title of Invention: LEADFRAME FOR SEMICONDUCTOR PACKAGE  
First Named Inventor: HYUNG LEE  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2004-02-09  
Effective Receipt Date: 2004-05-18  
Submission Type: Information Disclosure Statement  
Filing Type:  
Confirmation number: 8761  
Attorney Docket Number: AMKOR006C




Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: 17166f72be06ce740463ca112390f1a2cf2d5cff



## TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of Invention	LEADFRAME FOR SEMICONDUCTOR PACKAGE									
Application Number: 10/774893 										
Date: 2004-02-09										
First Named Applicant: HYUNG JU LEE										
Confirmation Number: 8761										
Attorney Docket Number: AMKOR006C										
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>										
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids4-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids4-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids4-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

LEADFRAME FOR SEMICONDUCTOR PACKAGE

Application Number: 10/774893



Confirmation Number: 8761

First Named Applicant: HYUNG LEE

Attorney Docket Number: AMKOR006C

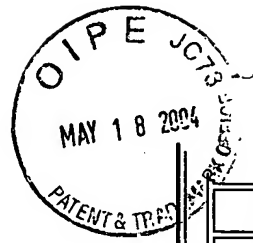
Art Unit: 2811

Search string: ( 5886398 or 5894108 or 5897339 or 5900676  
or 5903049 or 5903050 or 5909053 or 5915998  
or 5917242 or 5939779 or 5942794 or 5951305  
or 5959356 or 5969426 or 5973388 or 5976912  
or 5977613 or 5977615 or 5977630 or 5981314  
or 5986333 or 5986885 or 6001671 or 6013947  
or 6018189 or 6020625 or 6025640 or 6031279  
or 6034423 or RE36613 or 6040626 or 6043430  
or 6060768 or 6060769 or 6072228 or 6075284  
or 6081029 or 6084310 or 6087715 or 6087722  
or 6100594 or 6114752 or 6113474 or 6118174  
or 6118184 or 6130115 or 6130473 or RE36907  
or 6133623 or 6140154 ).pn.

### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5886398	1999-03-23	Low et al.			
	2	5894108	1999-04-13	Mostafazadeh et al.			
	3	5897339	1999-04-27	Song et al.			
	4	5900676	1999-05-04	Kweon et al.			
	5	5903049	1999-05-11	Mori			
	6	5903050	1999-05-11	Thurairajaratnam et al.			
	7	5909053	1999-06-01	Fukase et al.			
	8	5915998	1999-06-29	Stidham et al.			
	9	5917242	1999-06-29	Ball			
	10	5939779	1999-08-17	Kim			



	11	5942794	1999-08-24	Okumura et al.
	12	5951305	1999-09-14	Haba
	13	5959356	1999-09-28	Oh
	14	5969426	1999-10-19	Baba et al.
	15	5973388	1999-10-26	Chew et al.
	16	5976912	1999-11-02	Fukutomi et al.
	17	5977613	1999-11-02	Takata et al.
	18	5977615	1999-11-02	Yamaguchi et al.
	19	5977630	1999-11-02	Woodworth et al.
	20	5981314	1999-11-09	Glenn et al.
	21	5986333	1999-11-16	Nakamura
	22	5986885	1999-11-16	Wyland
	23	6001671	1999-12-14	Fjelstad
	24	6013947	2000-01-11	Lim
	25	6018189	2000-01-25	Mizuno
	26	6020625	2000-02-01	Qin et al.
	27	6025640	2000-02-15	Yagi et al.
	28	6031279	2000-02-29	Lenz
	29	6034423	2000-03-07	Mostafazadeh et al.
	30	RE36613	2000-03-14	Ball
	31	6040626	2000-03-21	Cheah et al.
	32	6043430	2000-03-28	Chun
	33	6060768	2000-05-09	Hayashida et al.
	34	6060769	2000-05-09	Wark
	35	6072228	2000-06-06	Hinkle et al.
	36	6075284	2000-06-13	Choi et al.
	37	6081029	2000-06-27	Yamaguchi
	38	6084310	2000-07-04	Mizuno et al.
	39	6087715	2000-07-11	Sawada et al.
	40	6087722	2000-07-11	Lee et al.
	41	6100594	2000-08-08	Fukui et al.
	42	6114752	2000-09-05	Huang et al.
	43	6113474	2000-09-05	Costantini et al.
	44	6118174	2000-09-12	Kim
	45	6118184	2000-09-12	Ishio et al.
	46	6130115	2000-10-10	Okumura et al.



	47	6130473	2000-10-10	Mostafazadeh et al.
	48	RE36907	2000-10-10	Templeton, Jr. et al.
	49	6133623	2000-10-17	Otsuki et al.
	50	6140154	2000-10-31	Hinkle et al.

Signature

Examiner Name	Date